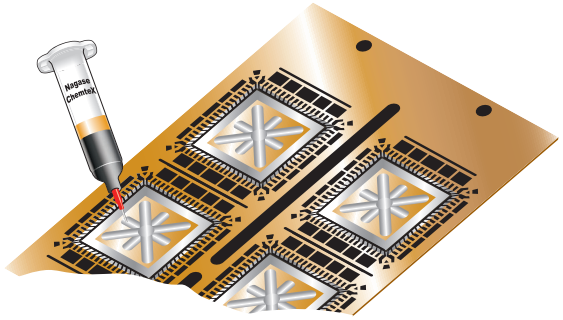
Electrically Conductive Die Attach



- **Rigid (small die)**
- **Flexible (large die)**
- **Low Cost**
- **Low Temp Cure**

PRODUCT	DESCRIPTION	RESISTIVITY (Ω•cm)	T_g TAN δ (ºC)	VISCOSITY 19 s^{-1} (cP)	THERMAL CONDUCTIVITY (W/m•K)	APPLICATION METHOD
Electrically Conductive Die and Component Attach Adhesives						
561-147-1	Low cost, moderate T_g, snap cure	4.0 x 10^{-4}	90	11,000	N/A	Needle & Jet dispense, Screen print
CA-152	Low cost, flexible ECA, acrylate	4.0 x 10^{-4}	14	18,000	N/A	Needle & Jet dispense, Screen print
CA-183	Low cost, Low temperature cure (80ºC) flexible ECA	9.0 x 10^{-3}	20	17,000	N/A	Needle & Jet dispense
CA-178	Electrically conductive die attach adhesive	1.5 x 10^{-4}	97	13,000	N/A	Needle dispense
High Thermal Conductivity, Electrically Conductive Die and Component Attach Adhesives						
CA-293	High thermal conductivity, extremely flexible die attach for power devices, large die	5.0 x 10^{-5}	-30	13,000	7	Pin transfer, Needle dispense
CA-188-2	High thermal conductivity, low temperature cure (80ºC), low stress solution	7.0 x 10^{-4}	62	17,000	5	Needle & Jet dispense
CA-196	High thermal conductivity, power devices, small die, LED's, long stage time	2.0 x 10^{-5}	135	11,000	13	Pin transfer, Needle dispense
DA-5990-1	High thermal conductivity die attach for power devices and LED's	5.0 x 10^{-4}	140	10,000	20	Pin transfer, Needle dispense
DB-1588-7	High thermal conductivity, flexible, low cost	4.0 x 10^{-4}	7	35,000	6	Stencil print

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